

**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application.

**Listing of Claims:**

Claims 1-40 (Canceled)

Claim 41 (Previously presented): The electronic component of claim 65, wherein the main body region comprises a curved portion.

Claim 42 (Canceled)

Claim 43 (Previously presented): The electronic component of claim 65, wherein the main body region is approximately parallel to a surface of the electronic component.

Claim 44 (Previously presented): The electronic component of claim 65 wherein at least a portion of the main body region is displaced from the substrate by a distance of between about 5 and 200 mils (thousandths of an inch).

Claim 45 (Previously presented): The electronic component of claim 65 wherein at least a portion of the main body region is displaced from the substrate by a distance of between about 2 and 8 mils.

Claim 46 (Previously presented): The electronic component of claim 65, wherein said contact structure further comprises a sloped region disposed between the base region and the main body region.

Claims 47 and 48 (Canceled)

Claim 49 (Previously presented): The electronic component of claim 46 where the sloped region has an average angle of between about 60 and 75 degrees.

Claims 50-53 (Canceled)

Claim 54 (Previously presented): the electronic component of claim 65 wherein the conductive material comprises nickel.

Claim 55 (Previously presented): The electronic component of claim 65 wherein the conductive material comprises a material selected from the group consisting of nickel, copper, cobalt, iron, gold, silver, elements of the platinum group, noble metals, semi-noble metals, elements of the palladium group, tungsten, and molybdenum.

Claim 56 (Canceled)

Claim 57 (Previously presented): the electronic component of claim 65 wherein the substrate comprises a semiconductor device.

Claim 58 (Previously presented): The electronic component of claim 65 wherein the substrate comprises a semiconductor device that has been singulated from a wafer.

Claim 59 (Previously presented): The electronic component of claim 65 wherein the substrate comprises a device selected from the group consisting of a semiconductor device, a memory device, a portion of a semiconductor wafer, a space transformer, a ceramic device, a probe card, a chip carrier and a socket.

Claims 60-64 (Canceled)

Claim 65 (Currently amended): An electronic component comprising:

a substrate including a conductive area;

masking material formed on said substrate, said masking material patterned to form an opening corresponding to at least a portion of said conductive area and a main body portion;

conductive material deposited on said masking material within said opening and on said main body portion, said conductive material composing a contact structure comprising:

a base region electrically connected to said conductive area and formed within said opening, and

a main body region formed on said main body portion of said masking material, said main body region being integrally formed with said base region and displaced away from said substrate, and

a contact tip structure on at least a side of said main body region that faces away from said substrate, said contact tip structure configured to contact and thereby make an electrical connection with another electronic component.

Claim 66 (Previously presented): The electronic component of claim 65, wherein said masking material comprises a plurality of masking layers.

Claim 67 (Previously presented): The electronic component of claim 65, wherein said opening is tapered.

Claim 68 (Previously presented): The electronic component of claim 65, wherein said conductive area comprises a terminal on a surface of said substrate.

Claim 69 (Previously presented): The electronic component of claim 65 further comprising a terminal on a surface of said substrate, said terminal being electrically connected to said conductive area.

Claim 70 (Canceled)